

SMD1808-CW-H-R1 Datasheet

This 1808 chip LED light source is a high-performance energy-saving device. High reliability, high luminous intensity, high brightness consistency, small appearance size. It is suitable for LED backlight, electronic appliance indication application, display, mobile phone digital products, etc.

This part has a footprint that is compatible with most leds of the same size in today's market.



FEATURES

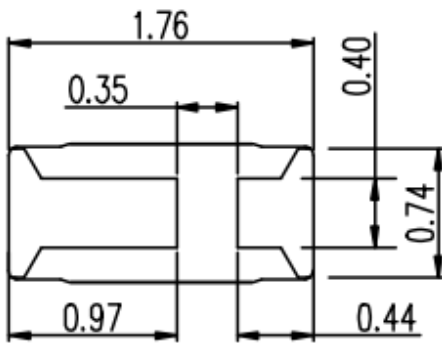
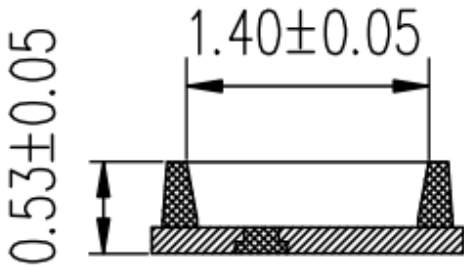
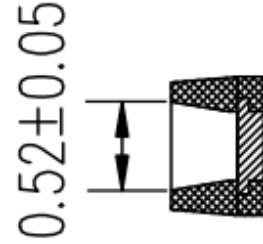
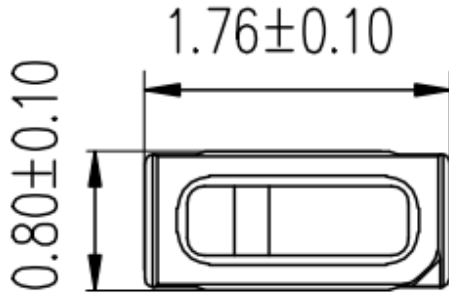
- High luminous Intensity and high efficiency
- Suitable for automatic patch machine
- Compatible with reflow soldering process
- Low thermal resistance
- Long operation life
- Wide viewing angle at 120°
- Silicone encapsulation
- Environmental friendly, RoHS compliance

APPLICATIONS

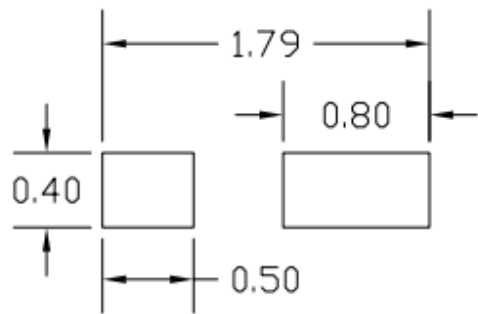
- Optical display
- Indoor display
- Automotive electronics display
- LED back light
- The computer
- Mobile digital
- Electrical switches and instructions

Note: The information in this document is subject to change without notice.

PACKAGE DIMENSIONS



背面图



PCB焊盘

Notes:

1. All dimensions in millimeters.
2. Thickness tolerance of copper plate is ± 0.02 mm.
3. Thickness tolerance of product is ± 0.05 mm.
4. Tolerance is ± 0.1 mm unless otherwise noted.

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Absolute Maximum Rating	Unit
Forward current	I_F	20	mA
Peak Forward Current ^[1]	I_{FP}	30	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_d	68	mW
Operating Temperature	T_{opr}	-40~+85	°C
Storage Temperature	T_{stg}	-40~+100	°C
Soldering Temperature	T_{sld}	Reflow Soldering: 260°C for 10 seconds	
LED Junction Temperature	T_j	115	°C

Note:

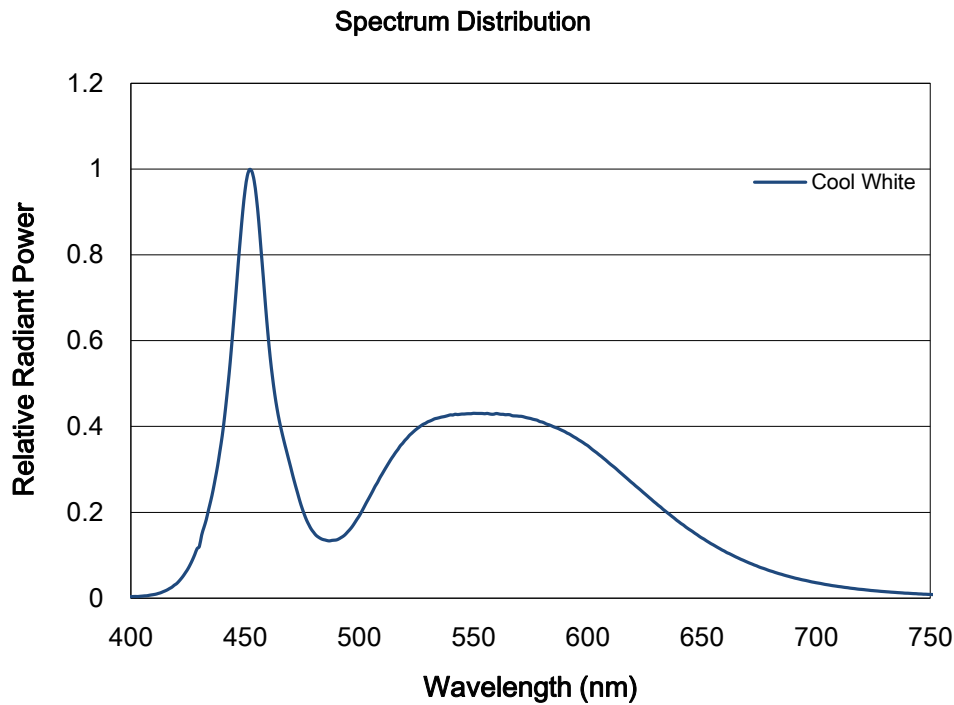
 I_{FP} Conditions: Pulse Width $\leq 10\text{msec.}$ and Duty $\leq 1/10$.CHARACTERISTICS ($T_j=25^\circ\text{C}$)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Forward Voltage ^[1]	V_F	IF=20mA	--	3.0	--	V
Viewing Angle	$2\theta_{1/2}$	IF=20mA	--	120	--	deg.
Luminous Flux	Φ_v	IF=20mA	--	1900	--	mcd
Color Coordinate	x	IF=20mA	--	0.25	--	--
	y	IF=20mA	--	0.24	--	--
Color Rendering Index	CRI	IF=20mA	80	--	--	--
Thermal Resistance (Junction to Solder Point)	R_{th-js}	IF=20mA	--	15	--	°C/W

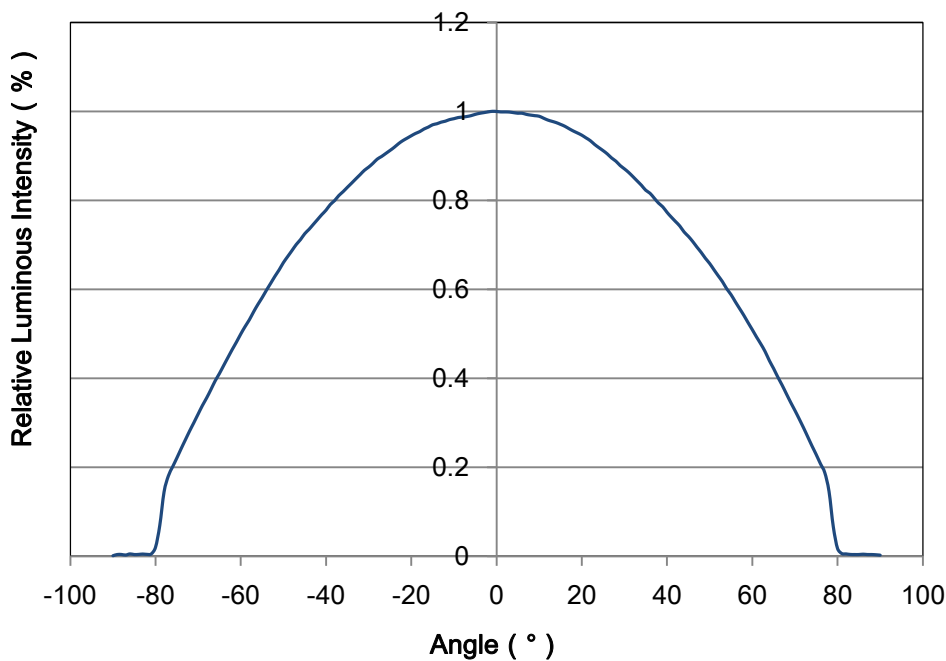
Notes:

1. Luminous flux is measured with an accuracy of $\pm 10\%$.
2. Chromaticity coordinate bins are measured with an accuracy of ± 0.01 .
3. CRI is measured with an accuracy of ± 2 .
4. Some color and CRI bins may have limited availability, please contact us before ordering.
5. All measurements were made under the standardized environment of Shineon

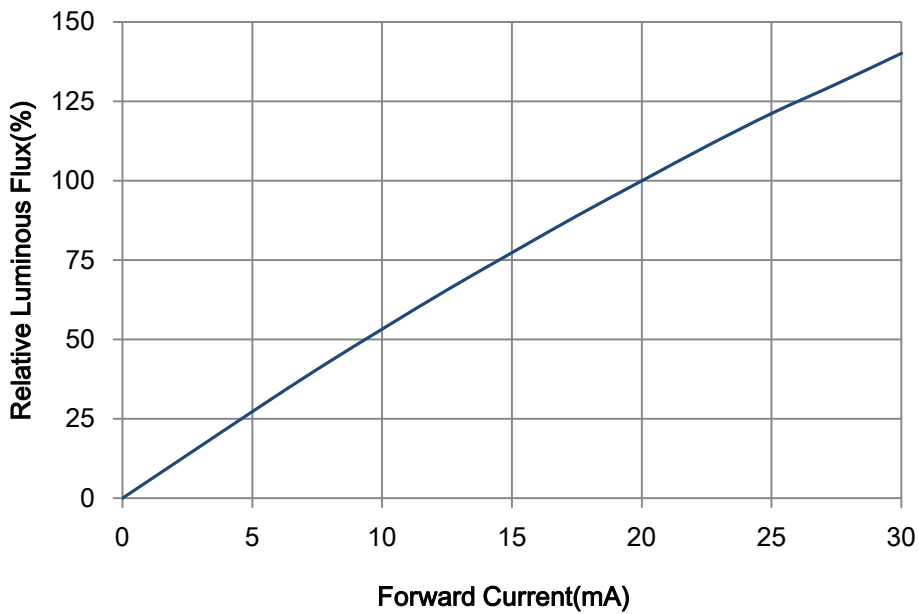
RELATIVE SPECTRAL POWER DISTRIBUTION (Ts=25℃)



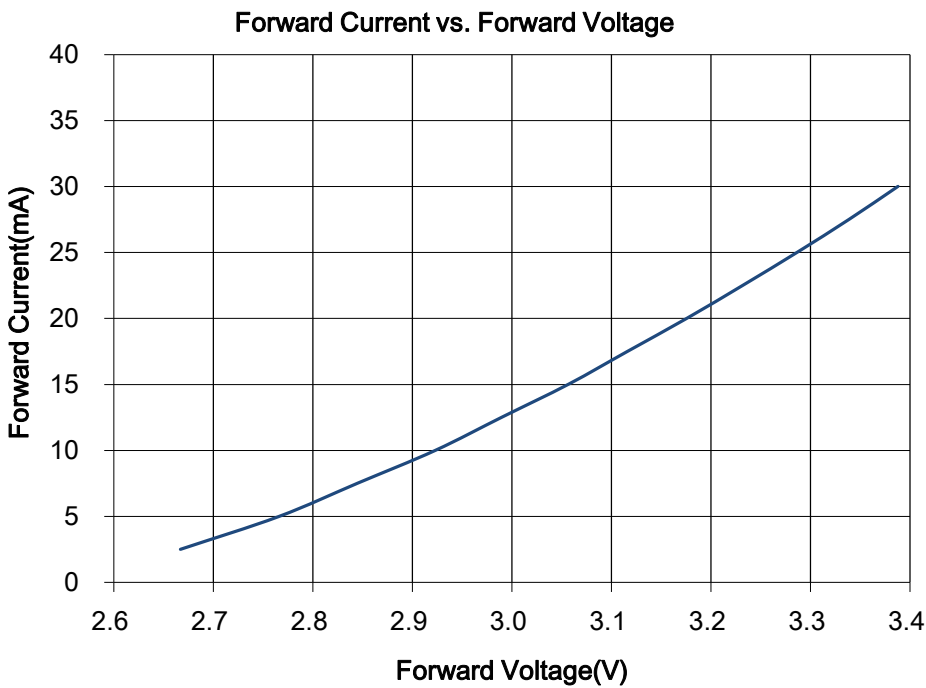
TYPICAL SPATIAL DISTRIBUTION



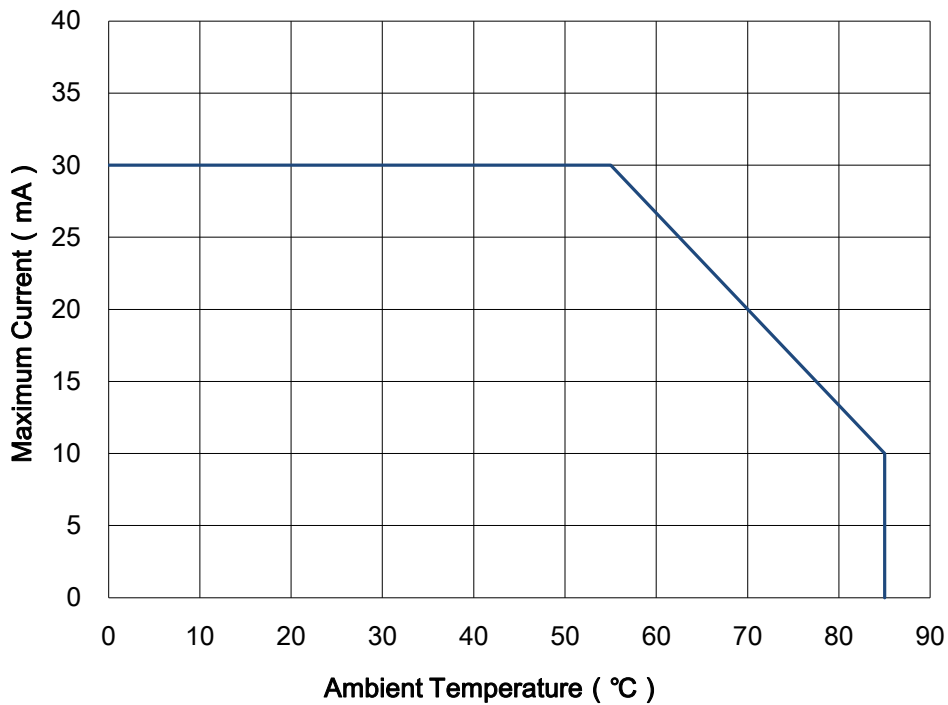
RELATIVE LUMINOUS FLUX VS. CURRENT (Ts=25℃)



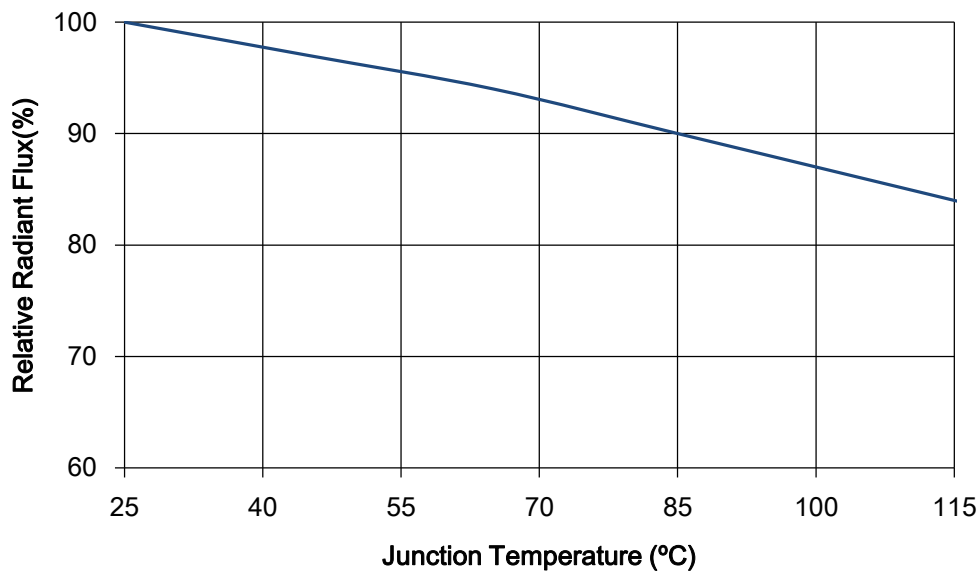
ELECTRICAL CHARACTERISTICS (Ts=25℃)



MAXIUM CURRENT VS. AMBIENT TEMPERATURE



RELATIVE RADIANT FLUX VS. JUNCTION TEMPERATURE



SORTING RANKS

(1) Luminous Flux (Ts=25°C)

Part Number	Rank (If =20mA)			Unit
SOM1808-CW-N-T	QV	QW	QX	mcd
	1500-1800	1800-2100	2100-2400	

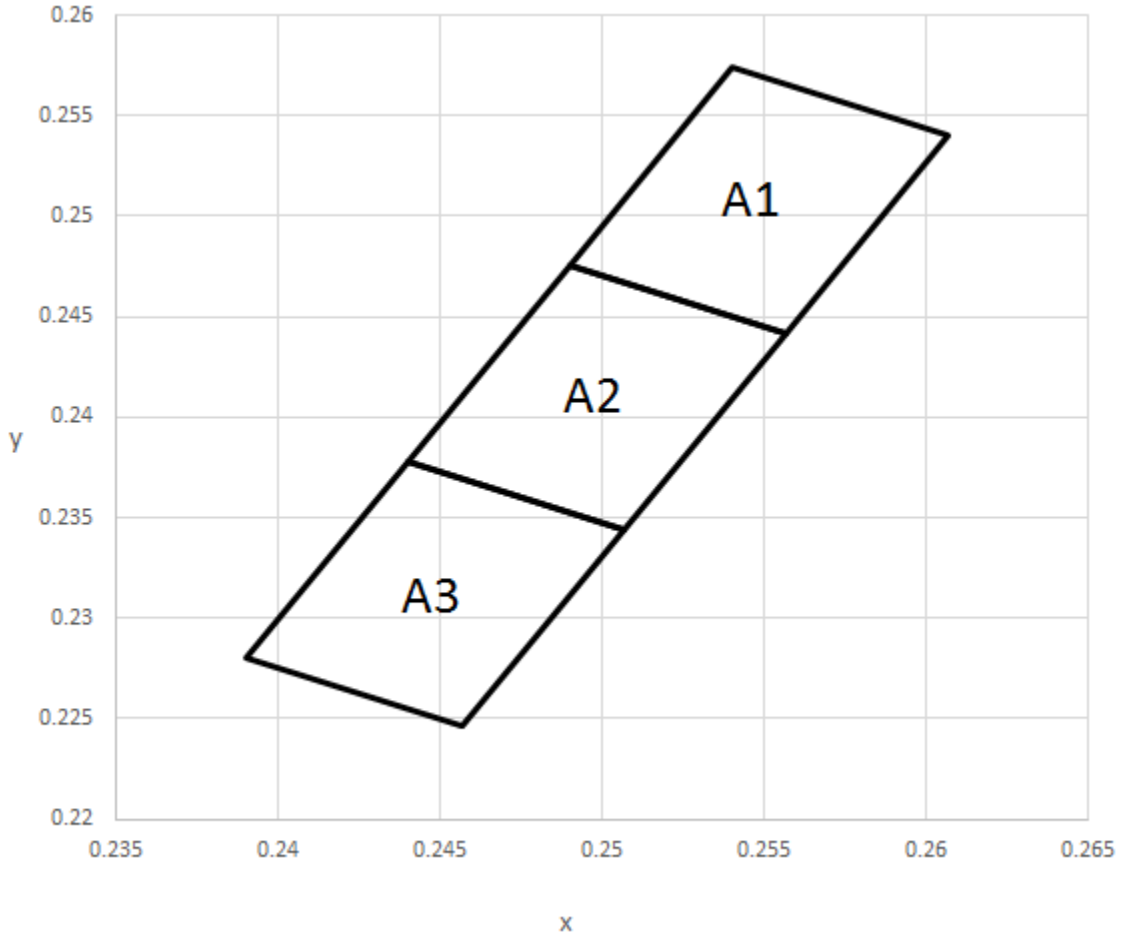
(2) Forward Voltage (Ts=25°C)

Rank	Condition	Min.	Max.	Unit
CE	20mA	2.8	2.9	V
DA		2.9	3.0	
DB		3.0	3.1	
DC		3.1	3.2	

Notes:

1. 5% tolerance for luminous intensity may be caused by measurement inaccuracy.
2. Measurement Uncertainty of the Forward Voltage : $\pm 0.1V$
3. Min lm bin <50% of total every shipment, CIE Bin 5+Bin 6 >70% of total every shipment for all color temperature

(3) Chromaticity Bins($T_s=25^{\circ}\text{C}$)



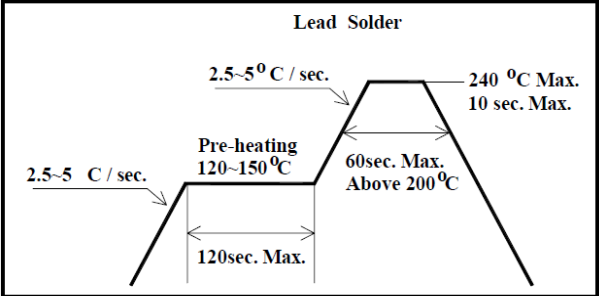
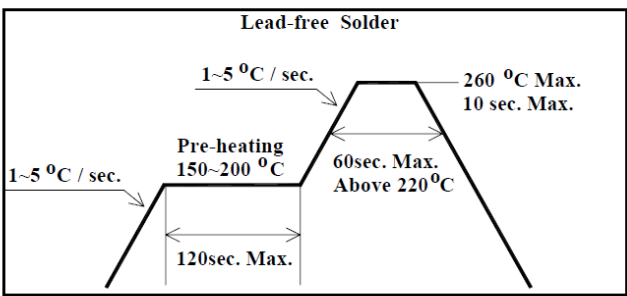
A1	X	0.249	0.254	0.2607	0.2557
	Y	0.2476	0.2574	0.254	0.2442
A2	X	0.244	0.249	0.2557	0.2507
	Y	0.2378	0.2476	0.2442	0.2344
A3	X	0.239	0.244	0.2507	0.2457
	Y	0.228	0.2378	0.2344	0.2246

REFLOW SOLDERING CHARACTERISTICS

For Reflow Process:

Preheating : 140℃~160℃±5℃,within 2 minutes.
 Operation heating : 260℃(Max.) within 10 seconds.(Max)
 Gradual Cooling (Avoid quenching).

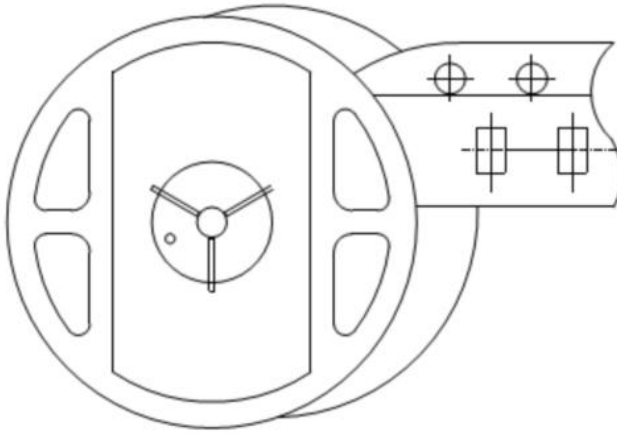
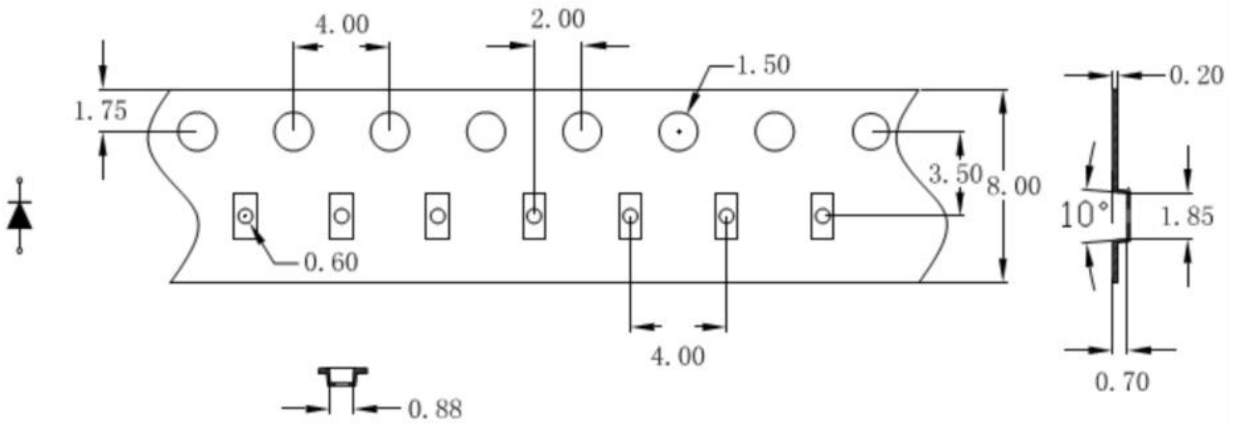
Lead solder		Lead-free solder	
Pre-heat	120-150℃	Pre-heat	150-200℃
Pre-heat time	120 sec.Max.	Pre-heat time	120 sec.Max.
Peak Temperature	240℃ Max.	Peak Temperature	260℃ Max.
Soldering time condition	10 sec.Max.	Soldering time condition	10 sec.Max.

<p>Lead Solder</p>  <p>The diagram shows a reflow profile for lead solder. It starts with a pre-heat phase at 120-150°C for a maximum of 120 seconds, heating at 2.5-5°C/sec. This is followed by a heating phase to 240°C at 2.5-5°C/sec, then a dwell at 240°C for a maximum of 10 seconds, and finally a cooling phase at 60°C/sec.</p>	<p>Lead-free Solder</p>  <p>The diagram shows a reflow profile for lead-free solder. It starts with a pre-heat phase at 150-200°C for a maximum of 120 seconds, heating at 1-5°C/sec. This is followed by a heating phase to 260°C at 1-5°C/sec, then a dwell at 260°C for a maximum of 10 seconds, and finally a cooling phase at 60°C/sec.</p>
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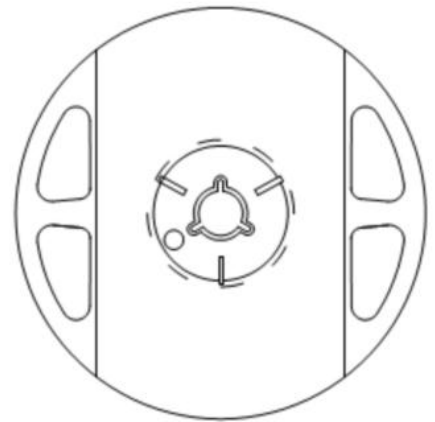
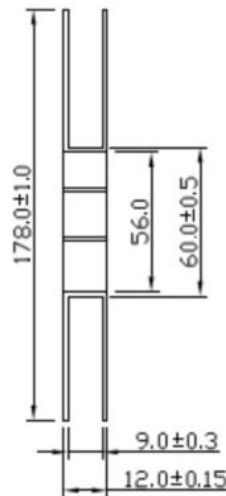
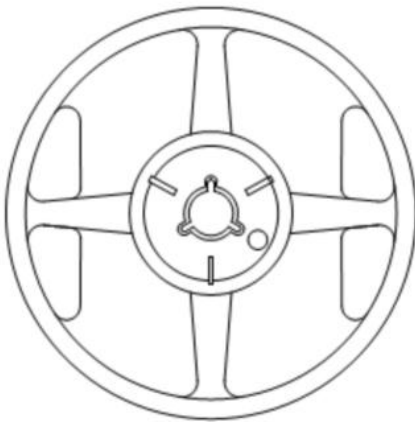
Notes:
 The encapsulated material of the LEDs is silicone . Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the picking up nozzle, the pressure on the silicone resin should be proper.

This product is qualified as Moisture sensitive Level 3 per JEDEC J-STD-020 Precaution when handing this moisture sensitive product is important to ensure the reliability of the product

TAPE AND REEL



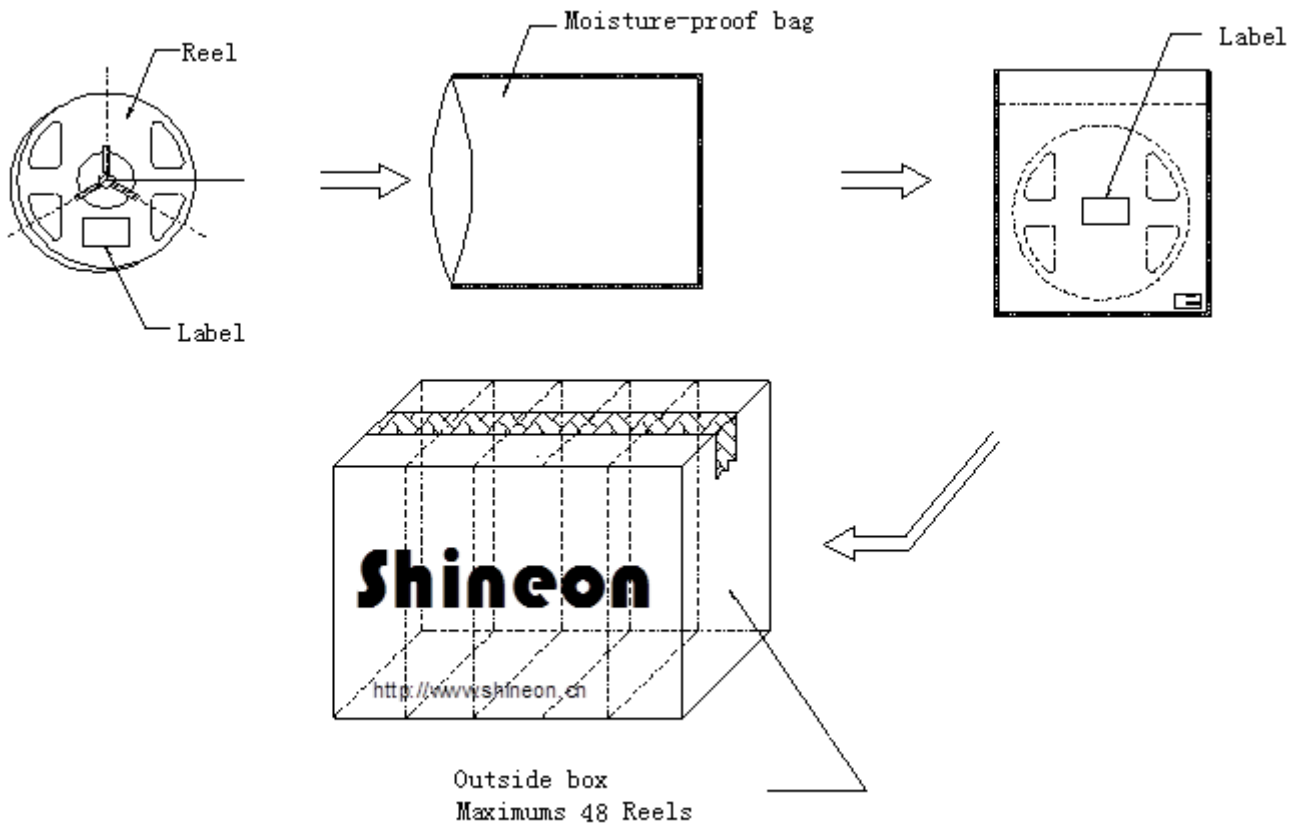
4000pcs/Reel



Notes:

- (1) Quantity : 4,000pcs/Reel
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be $\pm 0.2\text{mm}$
- (3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10° to the carrier tape
- (4) Package : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package.

PACKAGING



Mixed Loading of package rank and short package quantity

PRECAUTION FOR USE

- (1) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When washing is required, IPA should be used.
- (2) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.
- (3) LEDs must be stored to maintain a clean atmosphere. If the LEDs are stored for 3 months or more after being shipped from ShineOn, a sealed container with a nitrogen atmosphere should be used for storage.
- (4) The LEDs must be used within seven days after opening the moisture proof packing. Repack unused Products with anti-moisture packing, fold to close any opening and then store in a dry place.
- (5) The appearance and specifications of the product may be modified for improvement without notice.
- (6) This LED is sensitive to the static electricity and surge. It is recommended to use a wrist Band or anti-electrostatic glove when handling the LEDs.
- (7) On manual soldering, a solder tip must be needed as grounded for usage. If over voltage which exceeds the absolute maximum rating is applied to LEDs, it will cause damage LEDs and result in destruction. Damaged LEDs will show some unusual characteristics such as leak current remarkably increase ,turn-on voltage becomes lower and the LEDs get unlighted at low current.